

CLAIMS

1. A silicon containing curing composition comprising at least one silicon containing polymer selected from the following components (A), (B), and (C) and the following component (D) as a catalyst, provided that the composition contains
 - 5 both the components (A) and (B) when the component (C) is absent:
 - (A) A silicon containing polymer having at least one kind of a reactive group A' selected from the group consisting of Si-R¹, Si-O-R², and Si-R³-OCOC(R⁴)=CH₂, wherein R¹ and R² each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group; R³ represents an
 - 10 alkylene group having 1 to 9 carbon atoms and/or an arylene group; and R⁴ represents hydrogen or a methyl group,
 having an Si-O-Si bridge structure at at least one site thereof, and containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less.
 - 15 (B) A silicon containing polymer having an Si-H group, having an Si-O-Si bridge structure at at least one site thereof, and containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less.
 - (C) A silicon containing polymer having at least one kind of a reactive group A' selected from the group consisting of Si-R¹, Si-O-R², and Si-R³-OCOC(R⁴)=CH₂,
 - 20 wherein R¹ and R² each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group; R³ represents an alkylene group having 1 to 9 carbon atoms and/or an arylene group; and R⁴ represents hydrogen or a methyl group,
 and an Si-H group, having an Si-O-Si bridge structure at at least one site thereof, and
 - 25 containing 20% by weight or less of a component whose weight average molecular

weight is 1000 or less.

(D) A platinum-based catalyst as a catalyst for curing reaction.

2. The silicon containing curing composition according to claim 1, wherein the total aryl group and arylene group content of the total silicon containing polymers as

5 components (A), (B), and (C) is 0.1% to 50% by weight.

3. The silicon containing curing composition according to claim 1 or 2, which further comprises a metal oxide fine powder as component (E).

4. A cured product obtained by heat curing the silicon containing curing composition according to any one of claims 1 to 3.